

PCB PATTERN LAYOUT  
GENERAL TOLERANCE ±0.05

NOTES:

1. MATERIAL:

- 1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0;
- 1.2 CONTACT: COPPER ALLOY
- 1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:

2.1 CONTACT:

- 50u"~100u" NICKEL UNDERPLATING OVERALL.
- 1: GOLD FLASH PLATING
- L: 80u"~150u" PURE TIN ON CONTACT AREA AND SOLDER AREA.
- N: 80u"~150u" MATT TIN ON CONTACT AREA AND SOLDER AREA.
- C: 15U" GOLD ON CONTACT AREA ,G/F ON SOLDER AREA

2.2 FITTING NAIL:

- 50u"~100u" NICKEL UNDERPLATING OVERALL.
- 1: GOLD FLASH PLATING
- L: 80u"~150u" PURE TIN ON CONTACT AREA AND SOLDER AREA.
- N: 80u"~150u" MATT TIN ON CONTACT AREA AND SOLDER AREA.
- C: GOLD FLASH PLATING

3. REFLOW SOLDER CAPABLE TO 260°C  
PER ACES SPEC.

4. SPEC. PLS. REFER TO PS-50305-xxxx-xxx

5. PACKAGE PLS. REFER TO 88290-xxxx-TRP AND

88290-XXXX-07-TRP,88290-XXXX-U-TRP

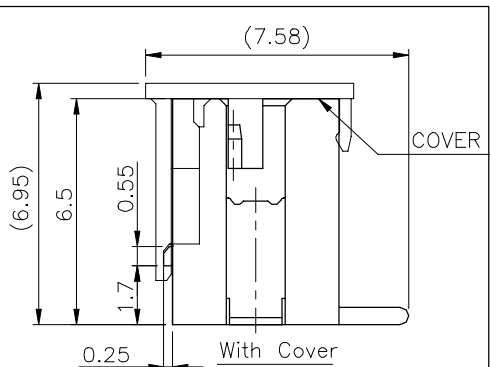
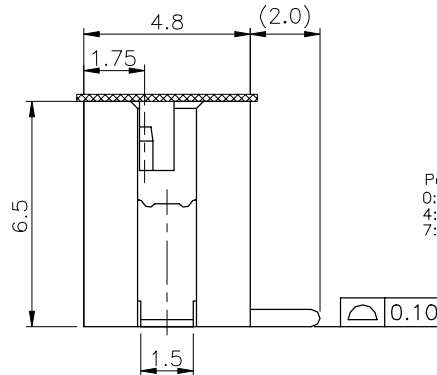
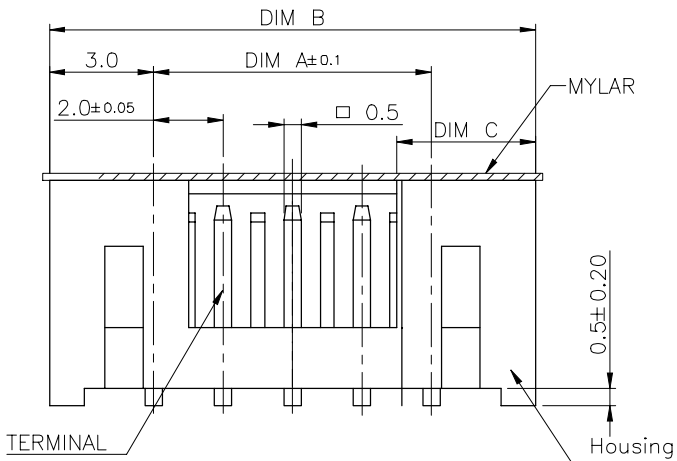
P/N LEGEND

50310-XXX X X-XXX

Others	Housing color	HALOGEN FREE	PACKING
001	BLACK	<b>HF</b>	88290-XXXX-TRP
002	NATURAL	<b>HF</b>	88290-XXXX-TRP
003	NATURAL	<b>HF</b>	88290-XXXX-07-TRP
004	NATURAL	<b>HF</b>	88290-XXXX-U-TRP

- CKTS
- Packing  
0:TAPE & REEL  
4:TAPE & REEL WITH MYLAR  
7:TAPE & REEL WITH COVER
- Plating  
1:GOLD FLASH  
L:PURE TIN LEAD FREE  
N:MATT TIN LEAD FREE  
C: 15U" GOLD ON CONTACT  
A: 3U" GOLD ON CONTACT

CKT	Dim A	Dim B
2	2.0	8.0
3	4.0	10.0
4	6.0	12.0
5	8.0	14.0
6	10.0	16.0
7	12.0	18.0
8	14.0	20.0
9	16.0	22.0
10	18.0	24.0
11	20.0	26.0
12	22.0	28.0
13	24.0	30.0
14	26.0	32.0
15	28.0	34.0
16	30.0	36.0
17	32.0	38.0
18	34.0	40.0
19	36.0	42.0
20	38.0	44.0



CKT	DIM C
2	3.50
OTHER	4.00

<b>QUALITY SYMBOLS</b> MAJOR Ⓢ CRITICAL Ⓢ	DRAWN BY Huang,ShunSen	DATE 21/06/29	
	CHECKED BY Lu, Jing Quan	DATE 21/06/29	
<b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b> X ±0.5 XX ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY hsieh, fu yu	DATE 21/06/29	<b>TITLE</b> 2.0mm WTB HEADER SMT S/T S/R H=6.5mm TYPE
	UNITS mm		SIZE A4
SCALE 5:1	SHEET NO. 1 OF 1	REV P	DWG NO. 50310-XXXX-XXX